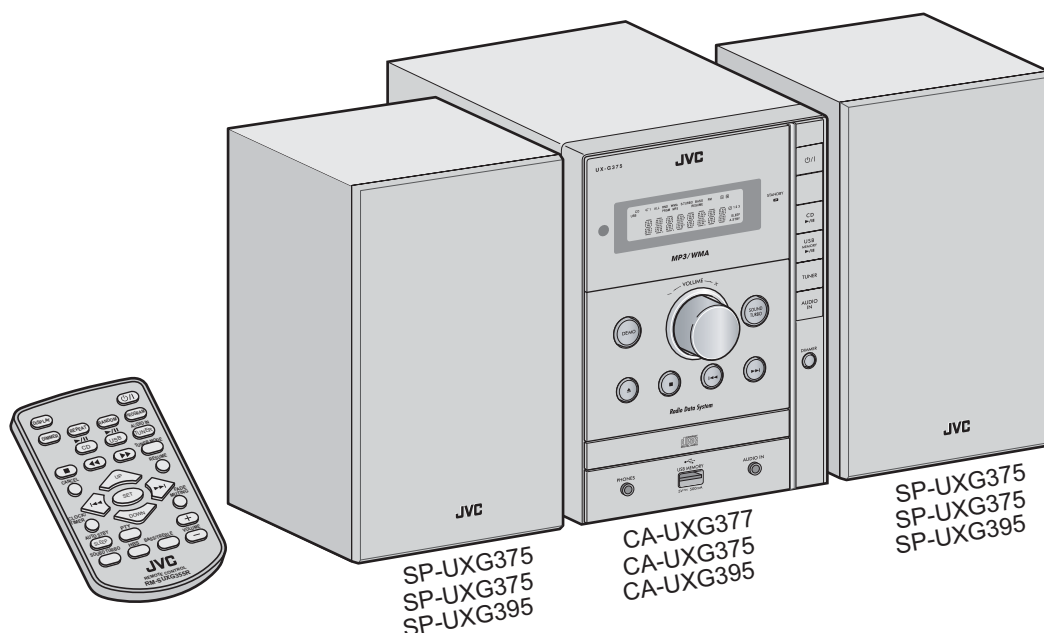


JVC

SCHEMATIC DIAGRAMS

MICRO COMPONENT SYSTEM

**UX-G375A, UX-G375B, UX-G375E, UX-G375EN,
UX-G375EV, UX-G375UP, UX-G375US,
UX-G375UT, UX-G375UW, UX-G377E,
UX-G377EN, UX-G377EV, UX-G377UT,
UX-G395BE, UX-G395BEN, UX-G395BEY,
UX-G395WE, UX-G395WEN, UX-G395WEY**



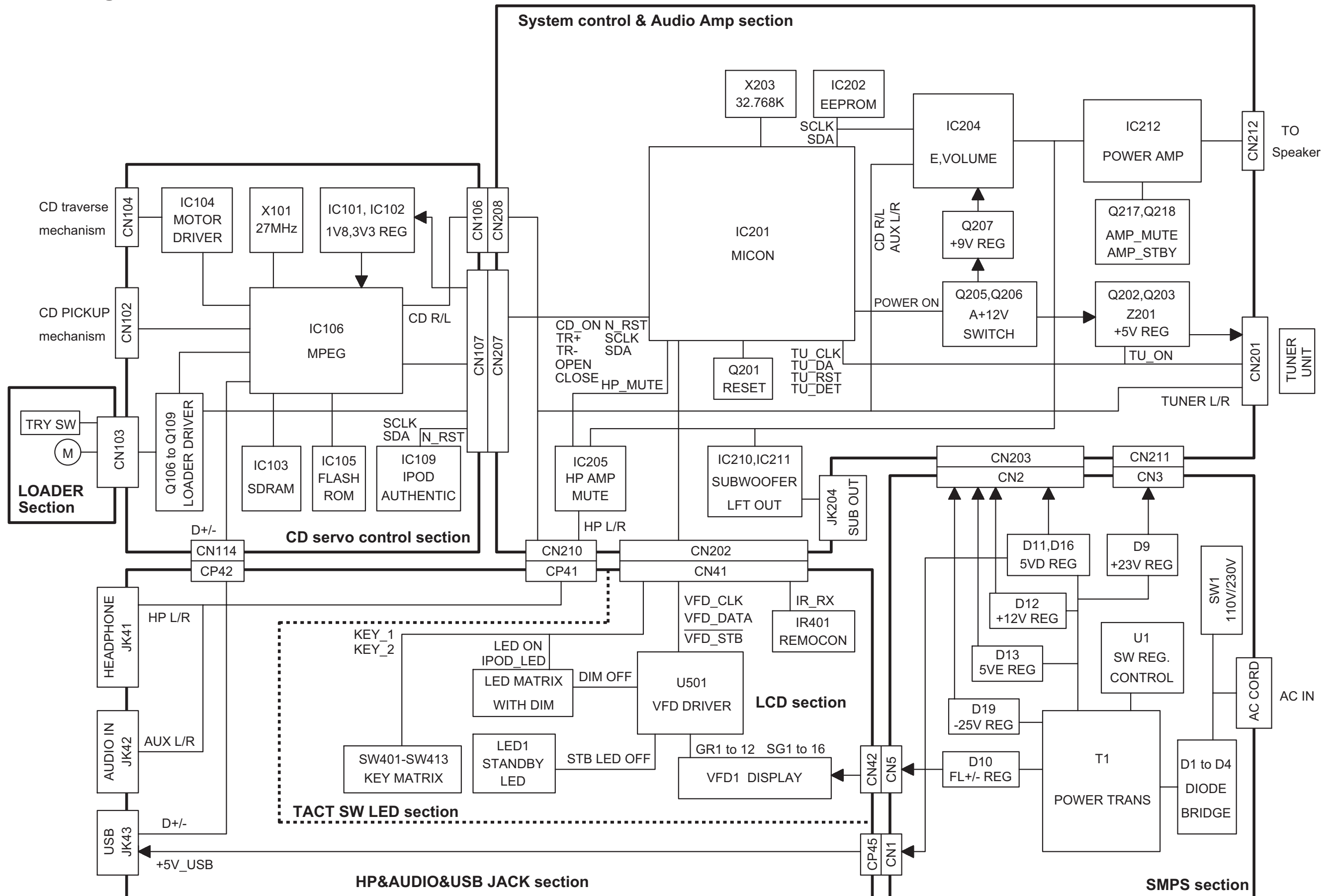
Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

Contents

Block diagrams	2-1
Standard schematic diagrams	2-2
Printed circuit boards	2-9 to 12

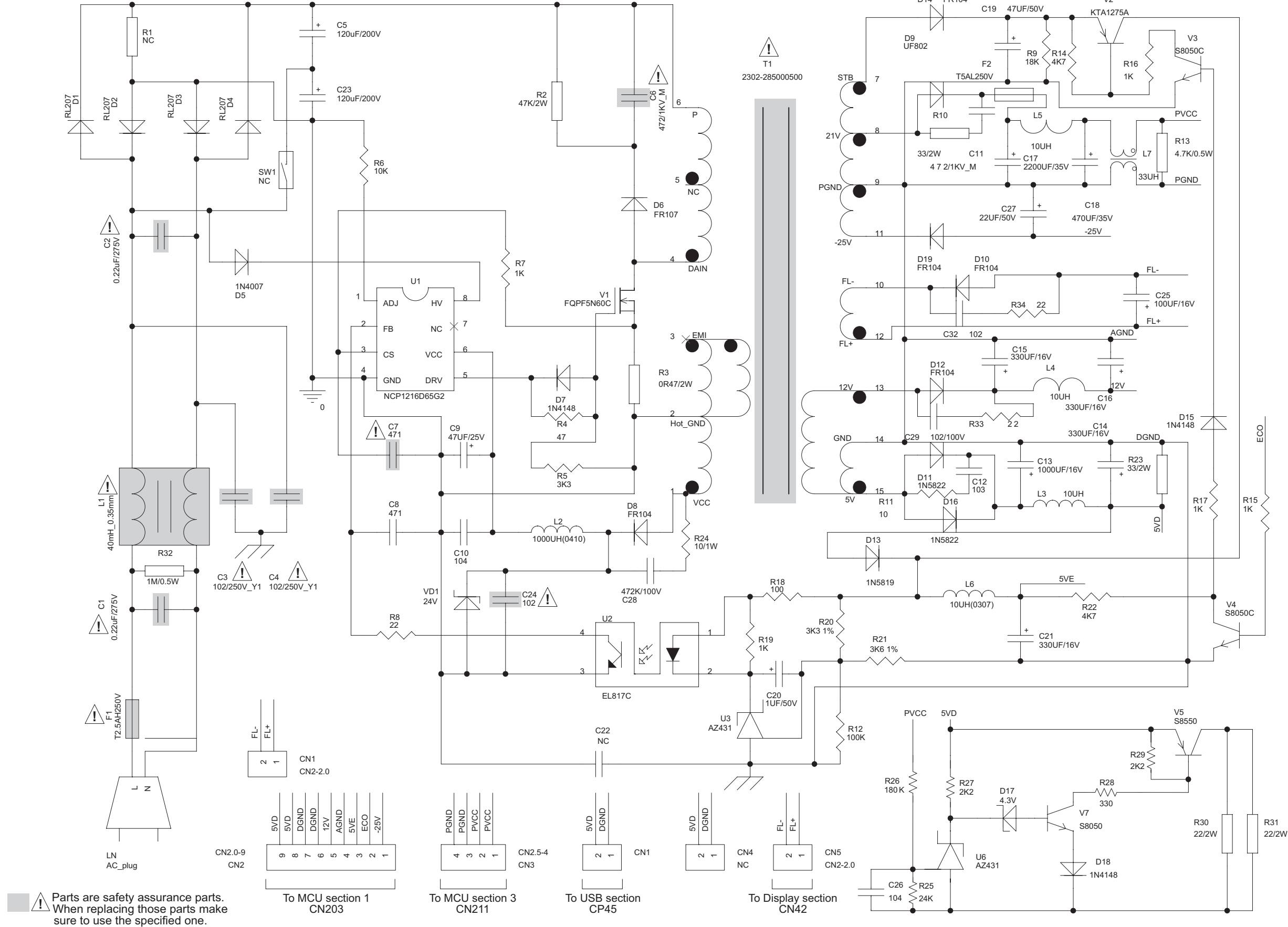
In regard with component parts appearing on the silk-screen printed side (parts side) of the PWB diagrams, the parts that are printed over with black such as the resistor (■), diode (▬) and ICP (●) or identified by the "A" mark nearby are critical for safety.

Block diagram

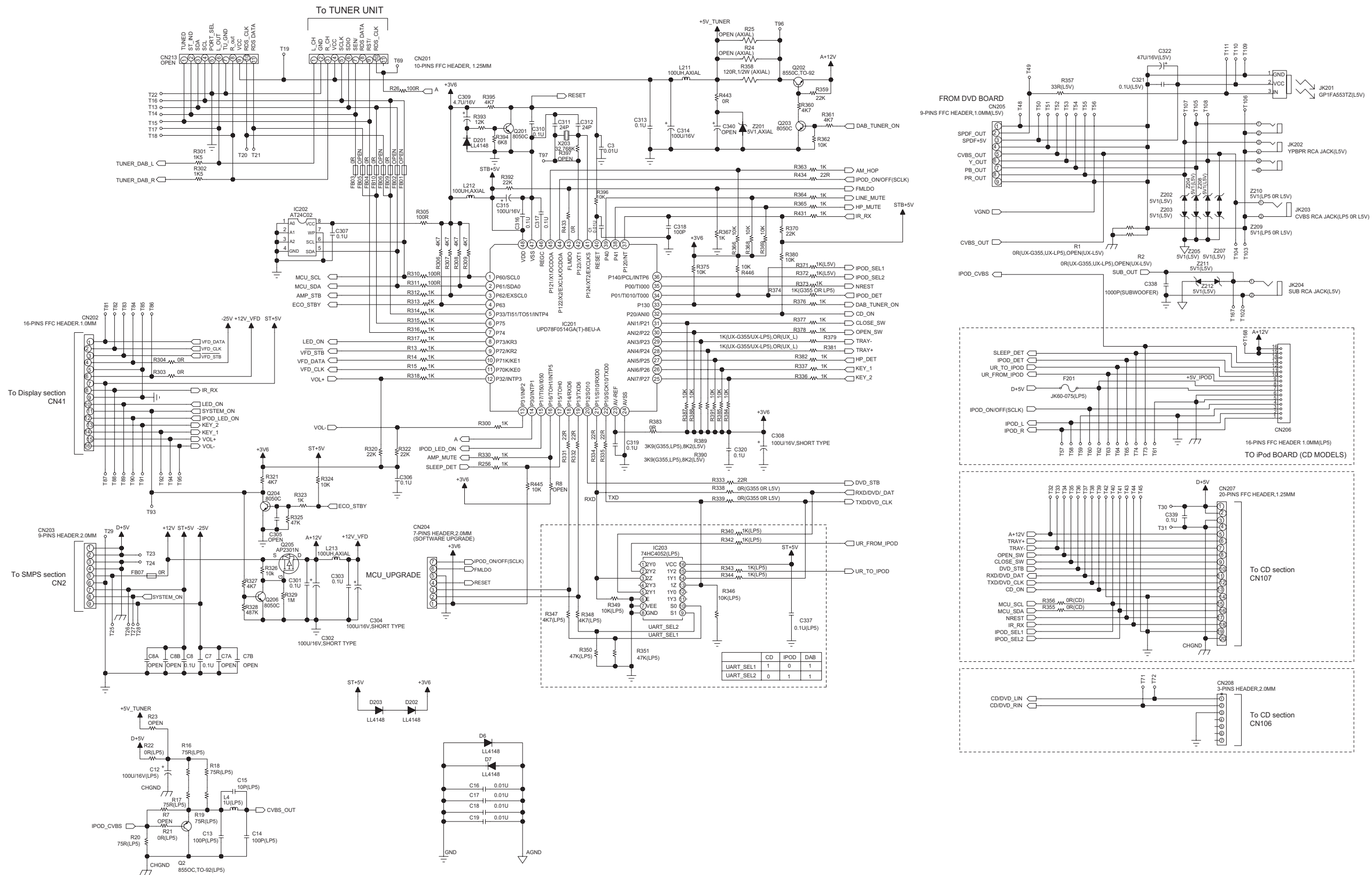


Standard schematic diagrams

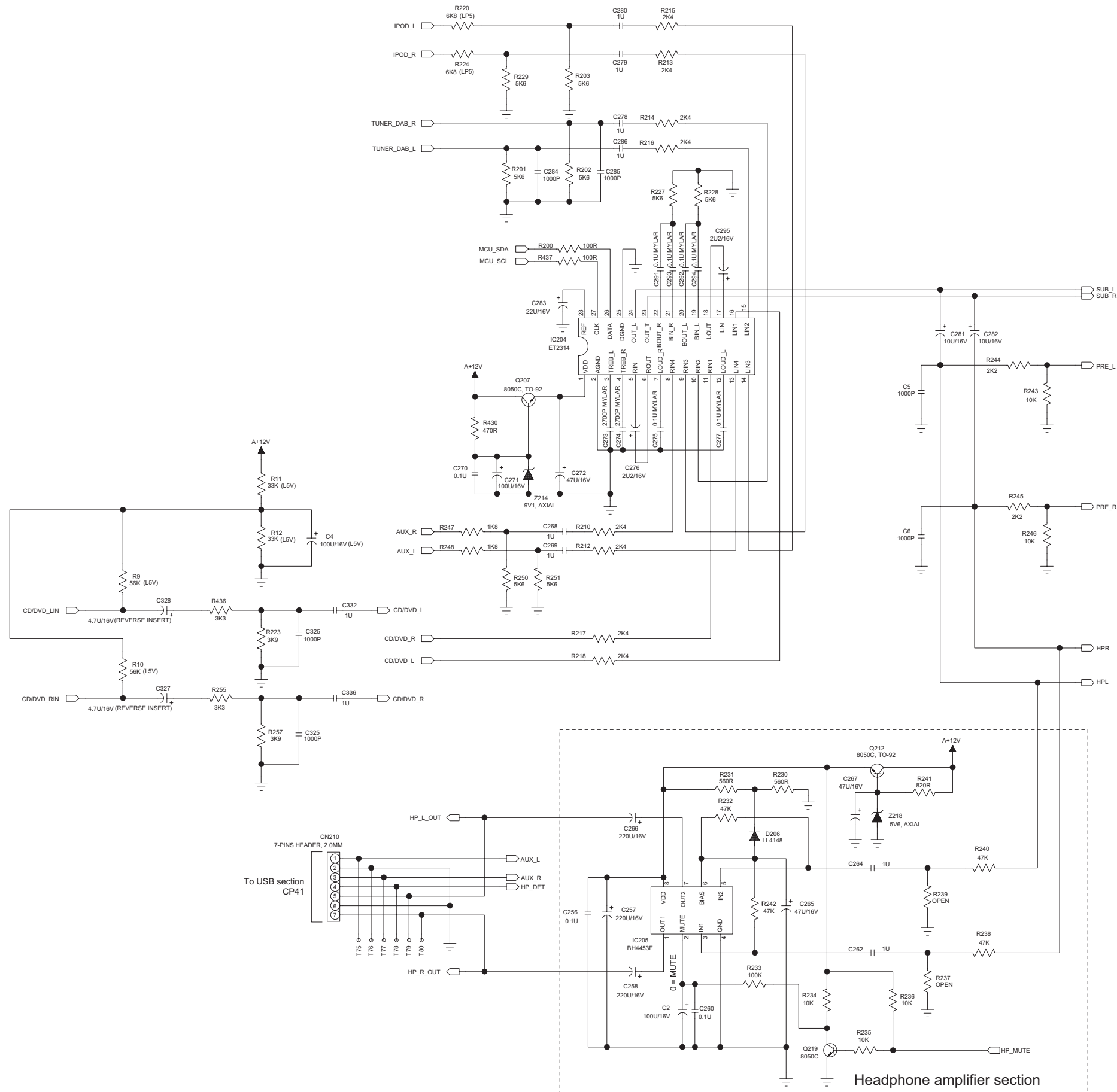
<SMPS Section>



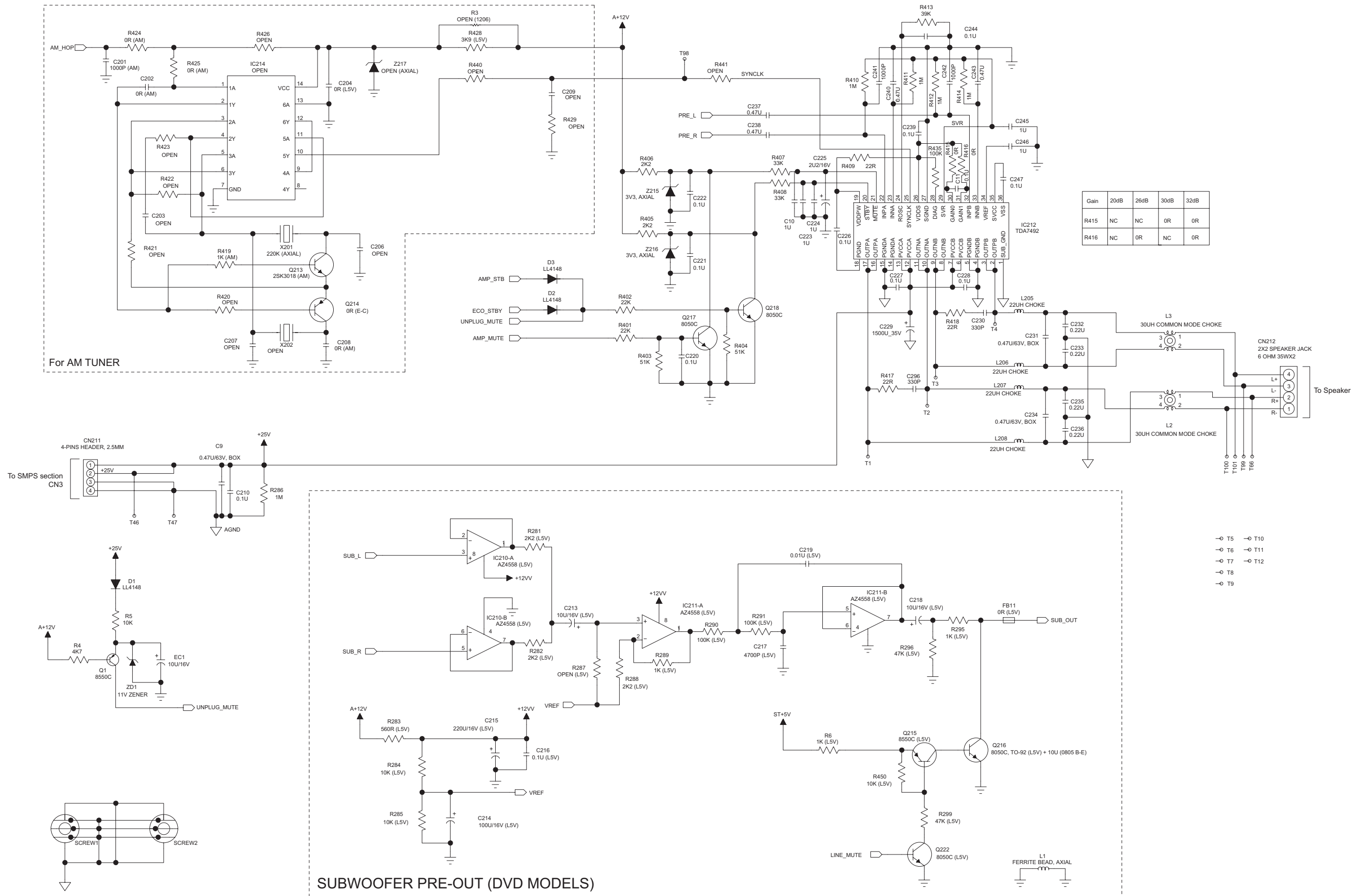
<MCU Section 1>



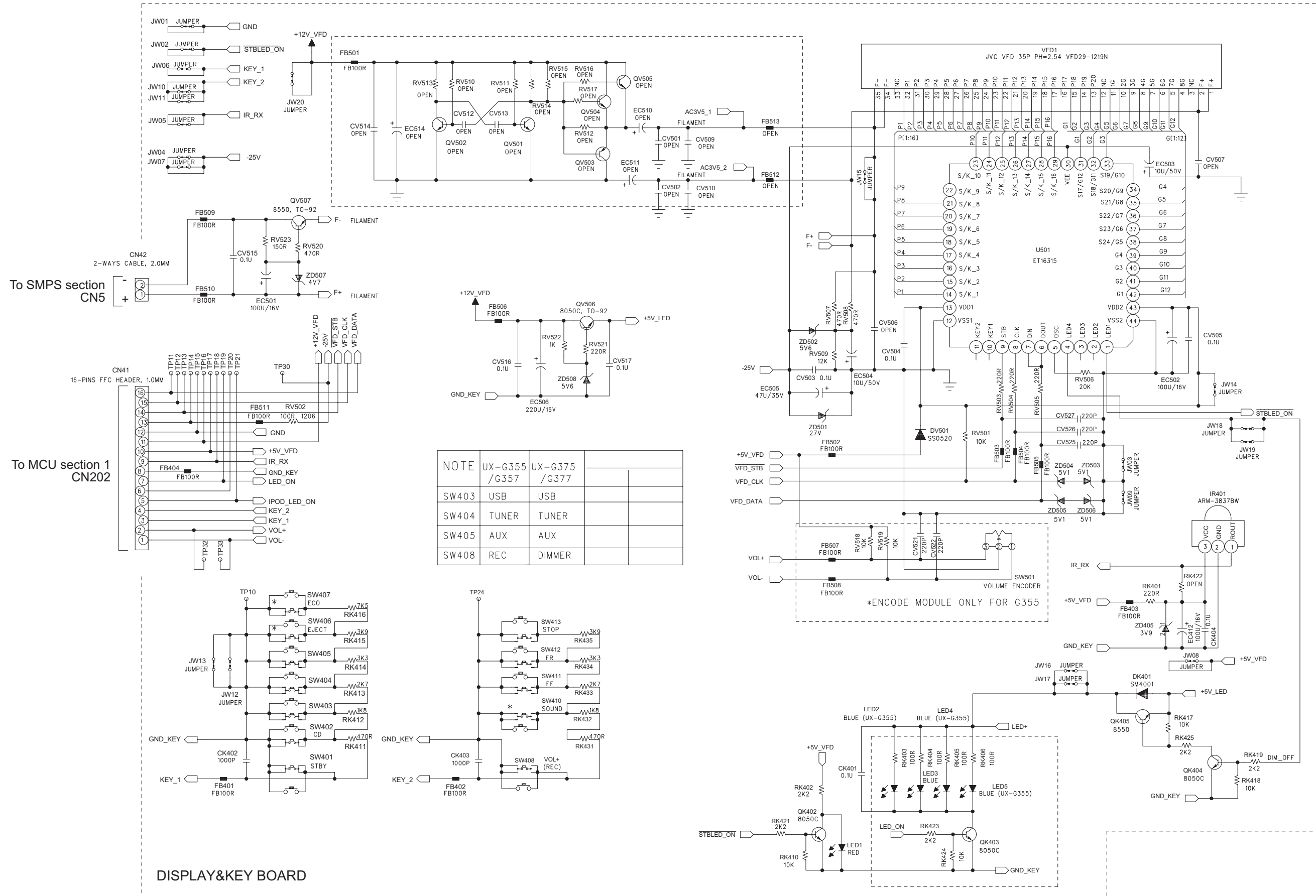
<MCU Section 2>



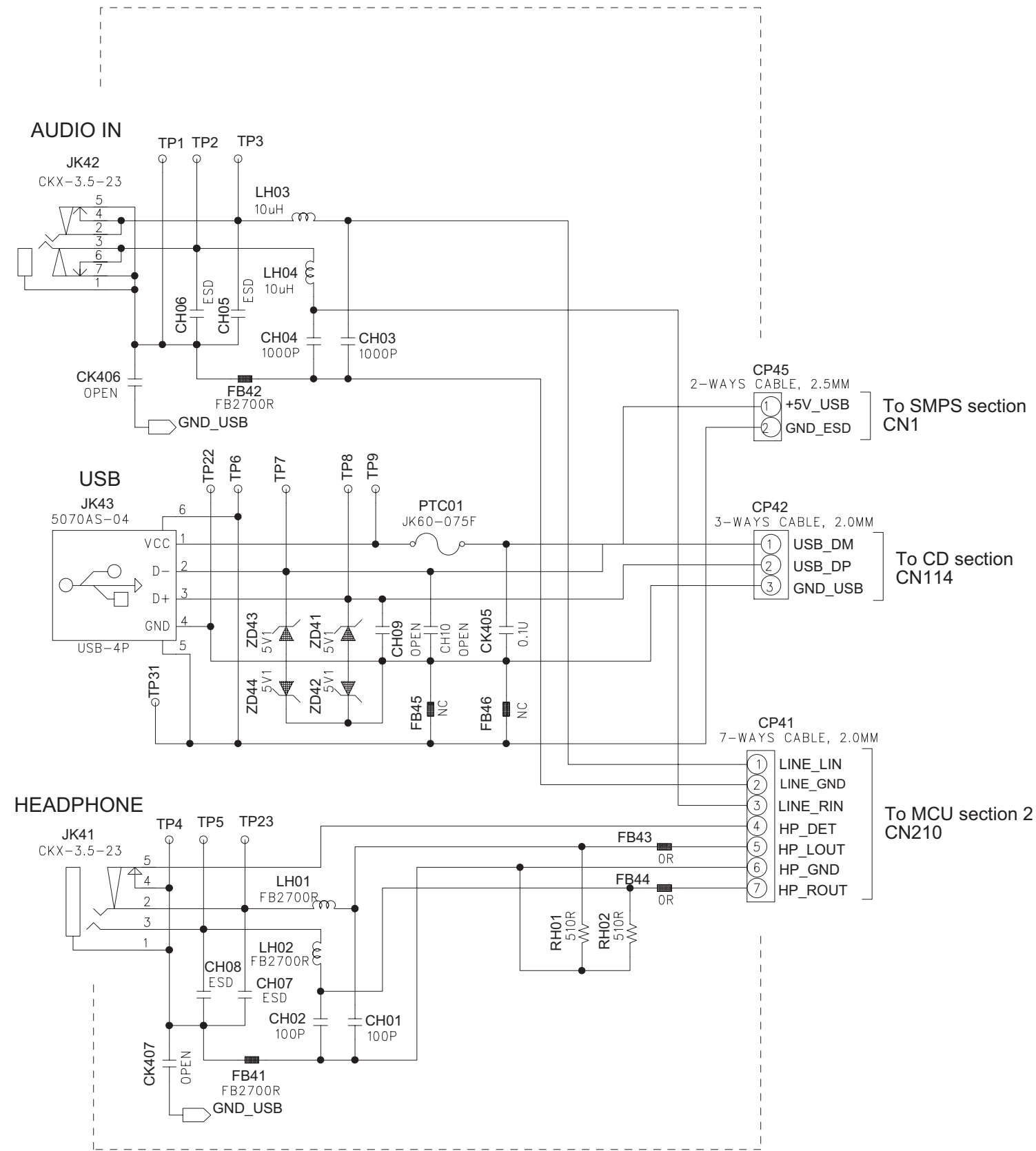
<MCU Section 3>



<Display section>

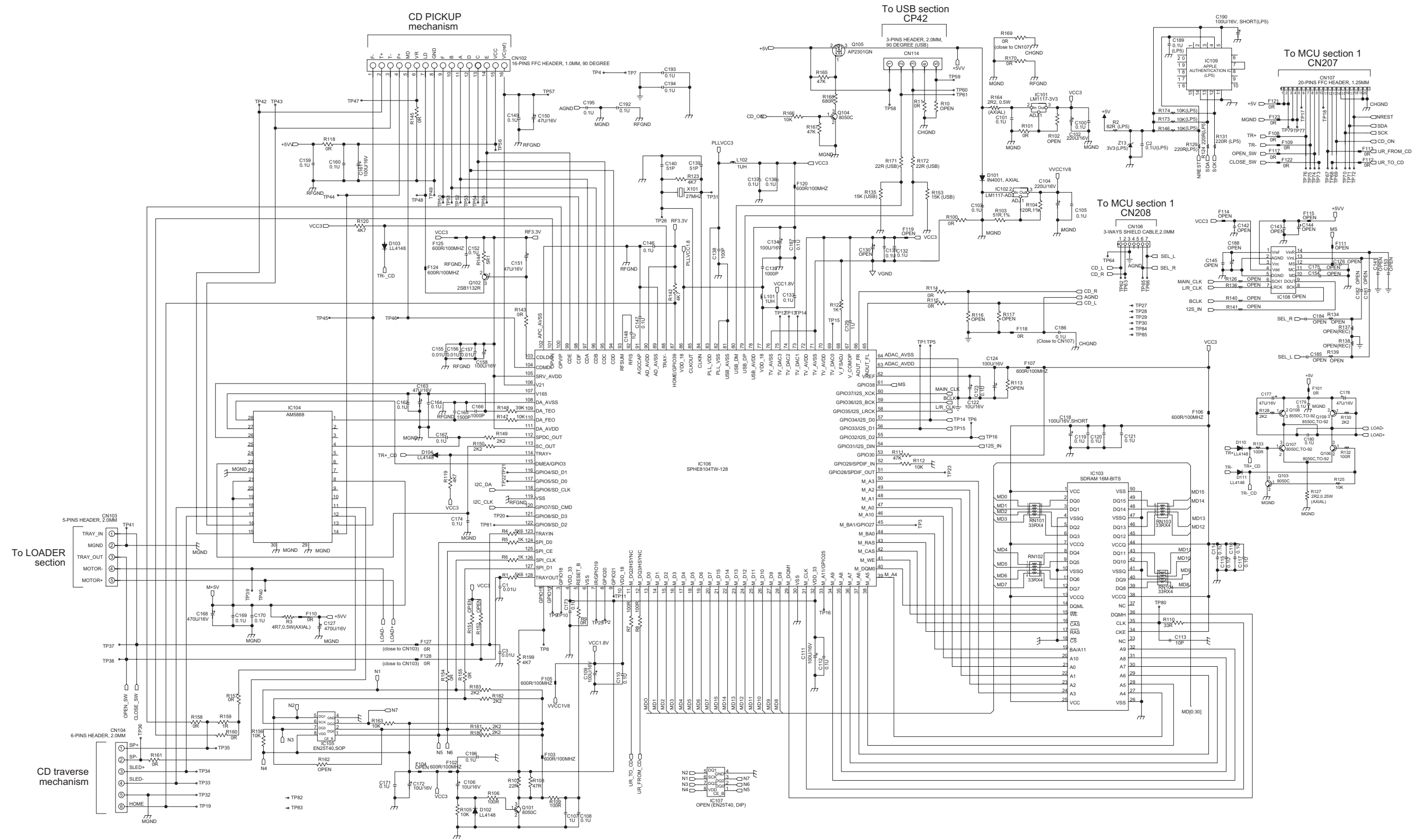


<USB section>



USB&PHONE&LINE-IN BOARD

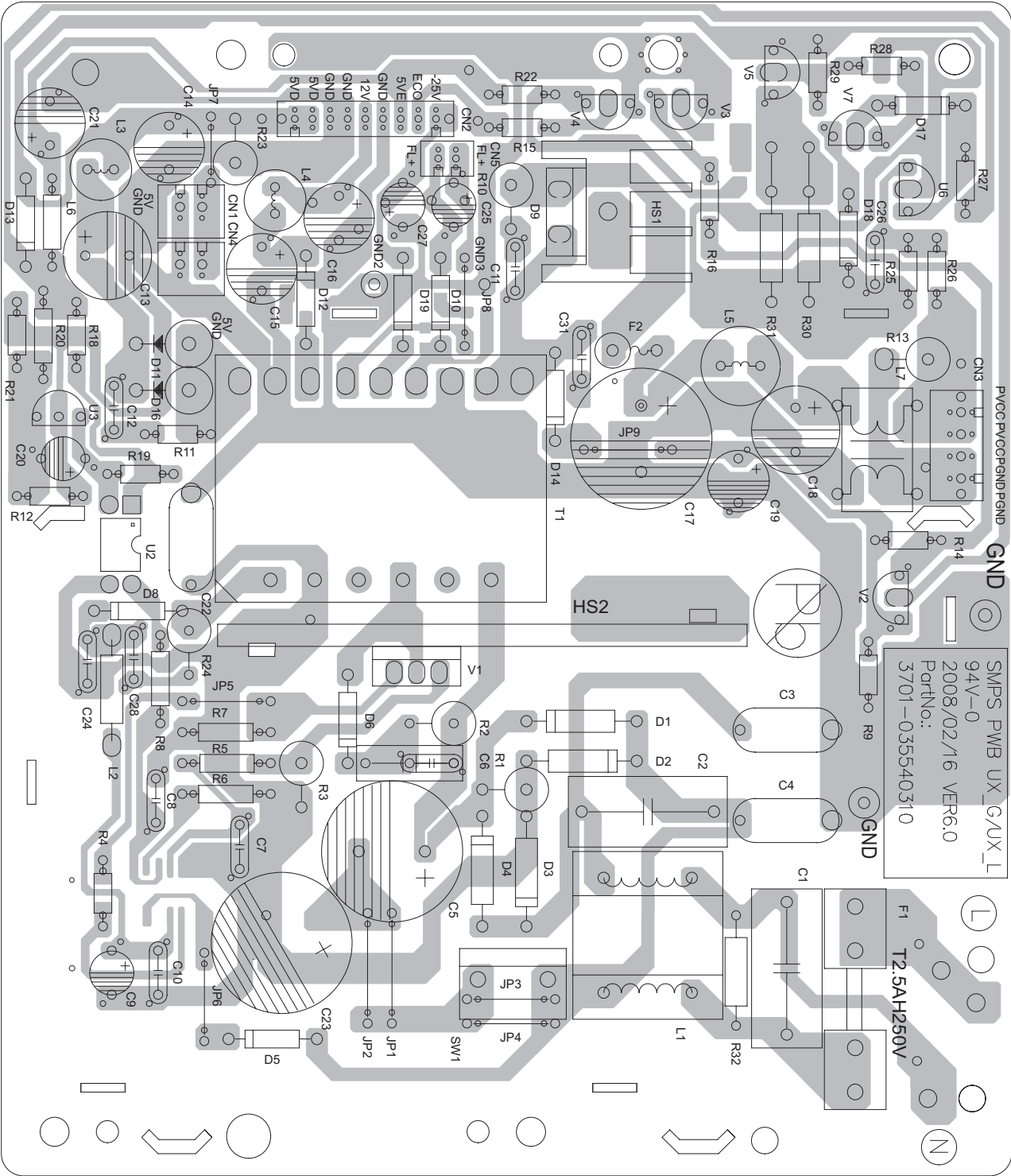
<CD section>



Printed circuit boards

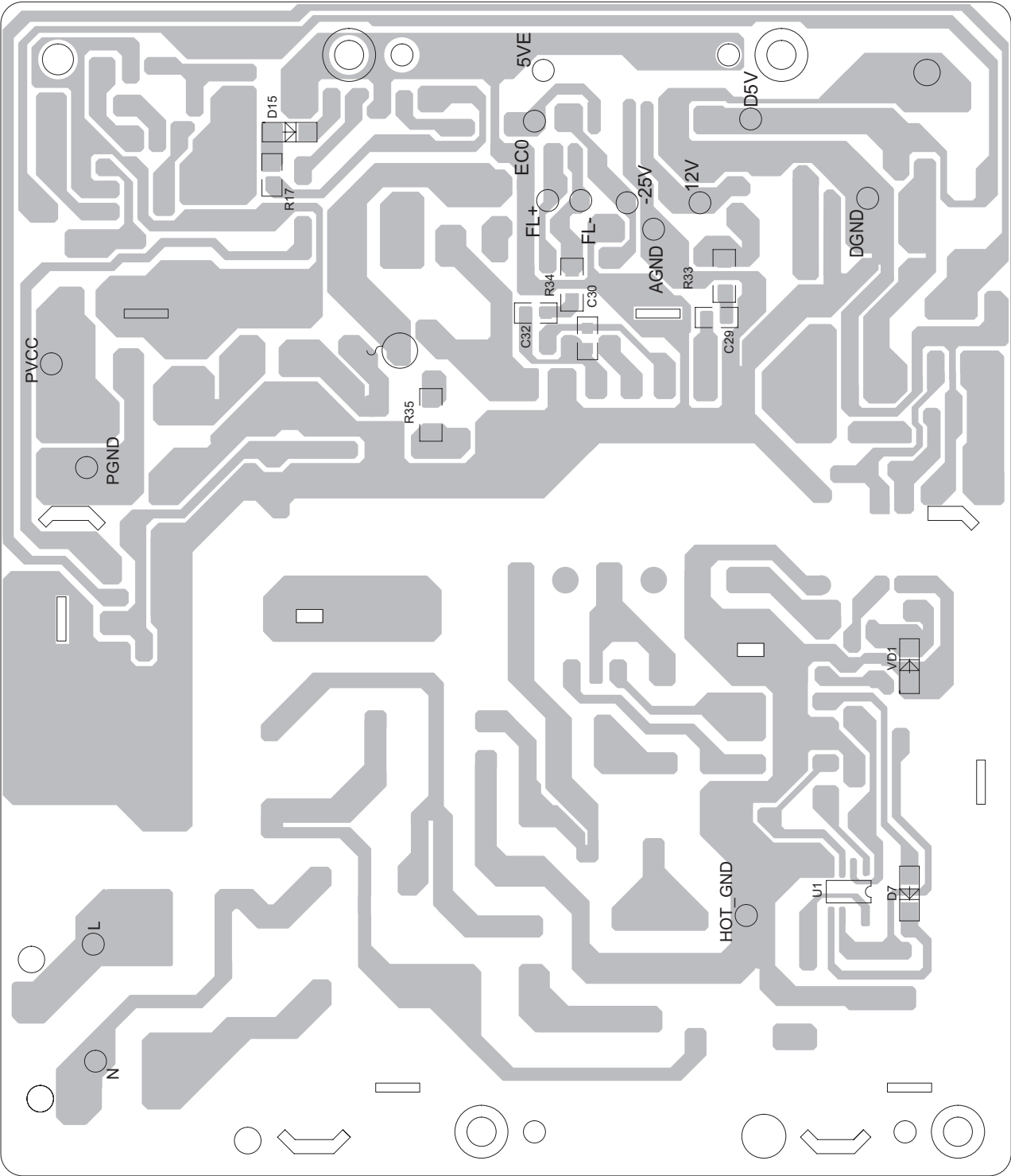
<SMPS board (forward side)>

(Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade))



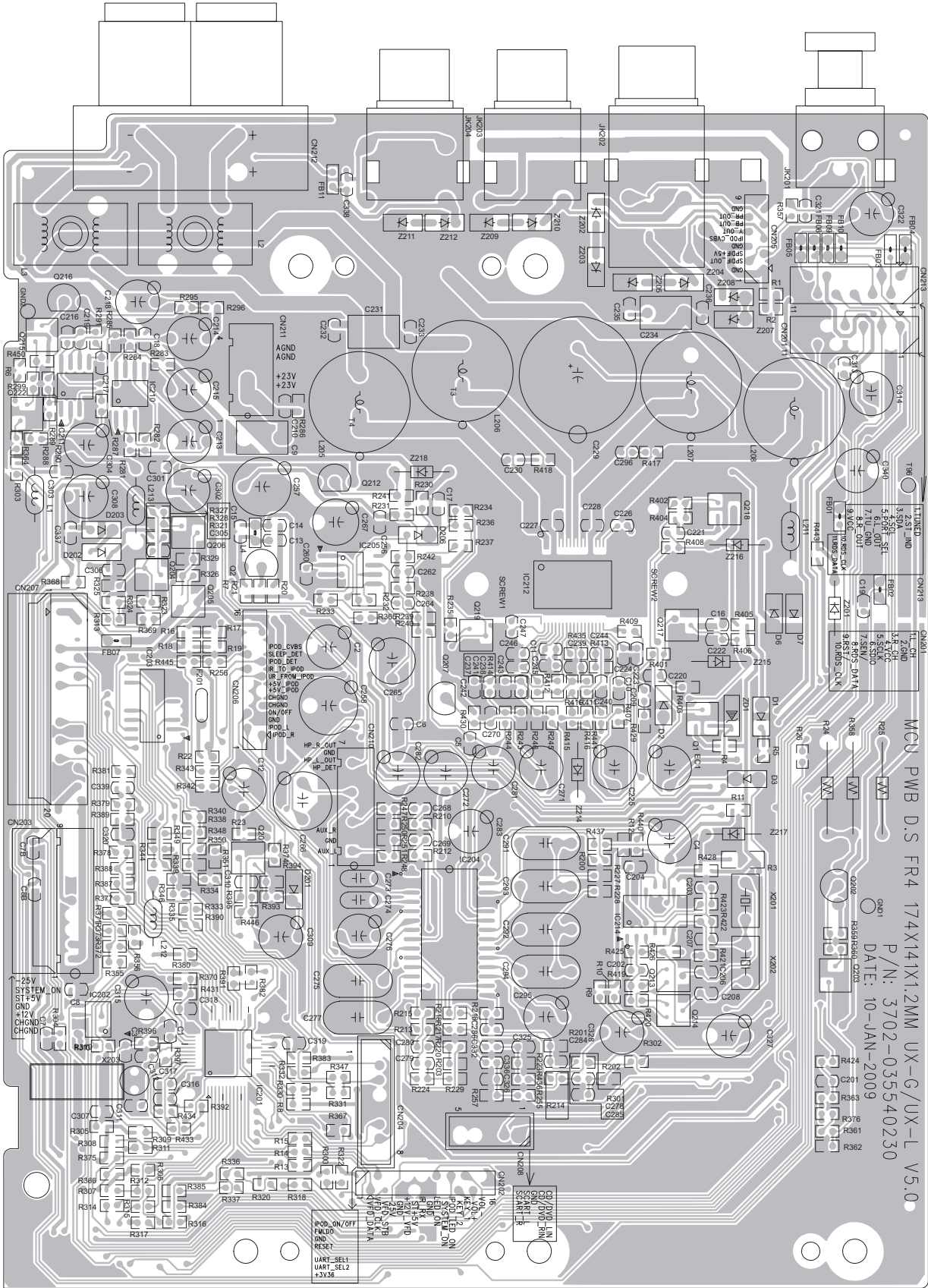
<SMPS board (reverse side)>

(Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade))



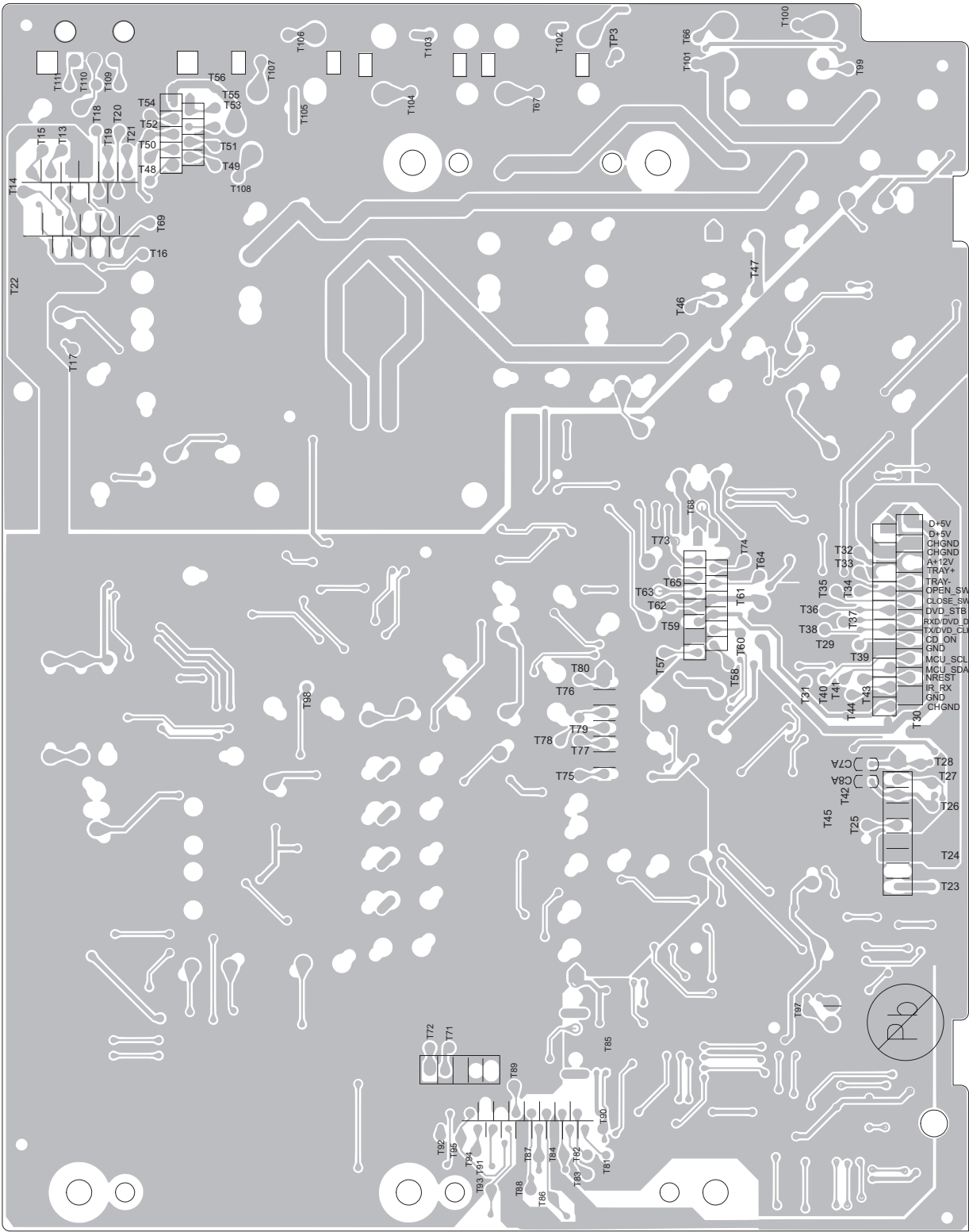
<MCU board (forward side)>

(Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade))



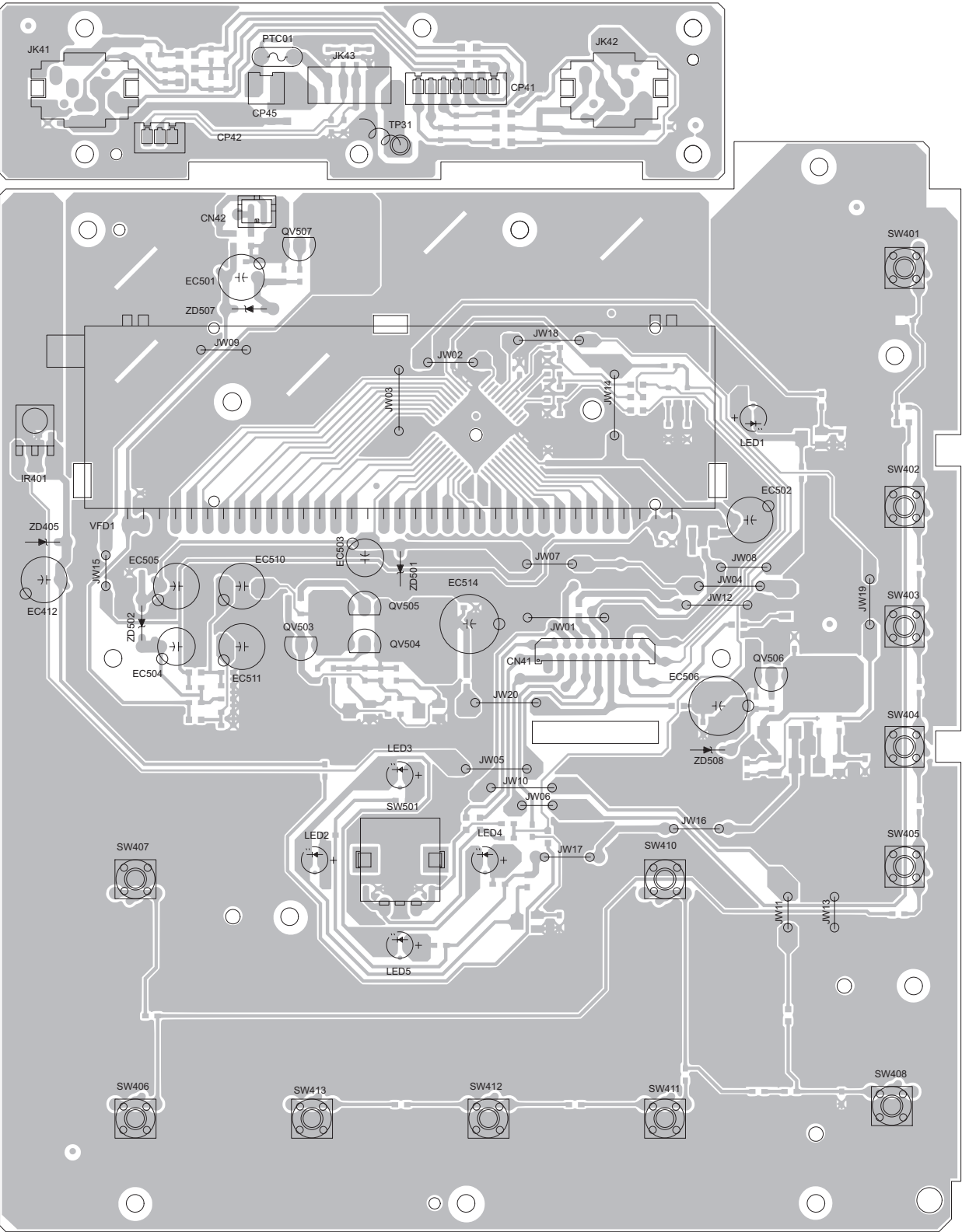
<MCU board (reverse side)>

(Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade))



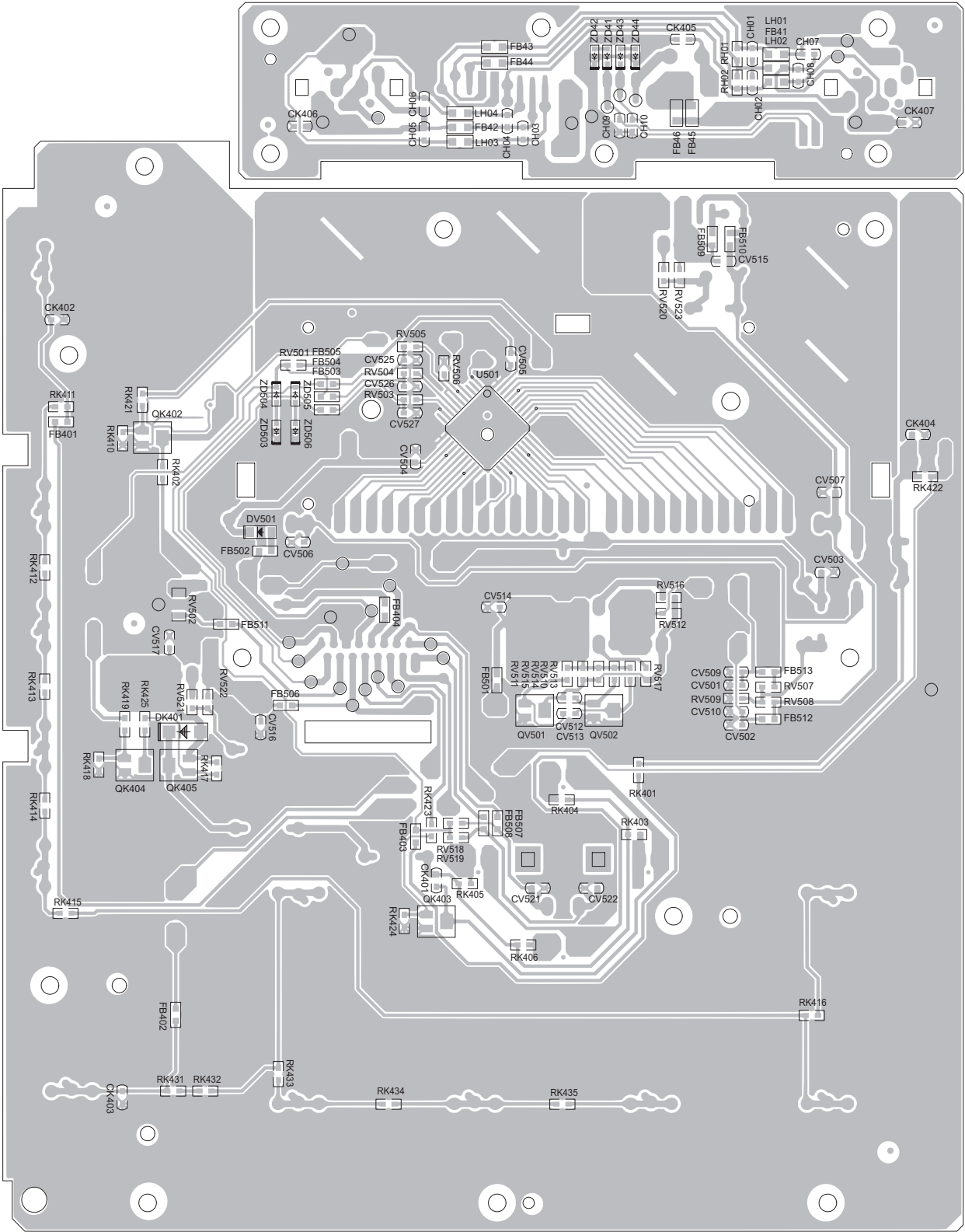
<Display/USB board (forward side)>

(Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade))

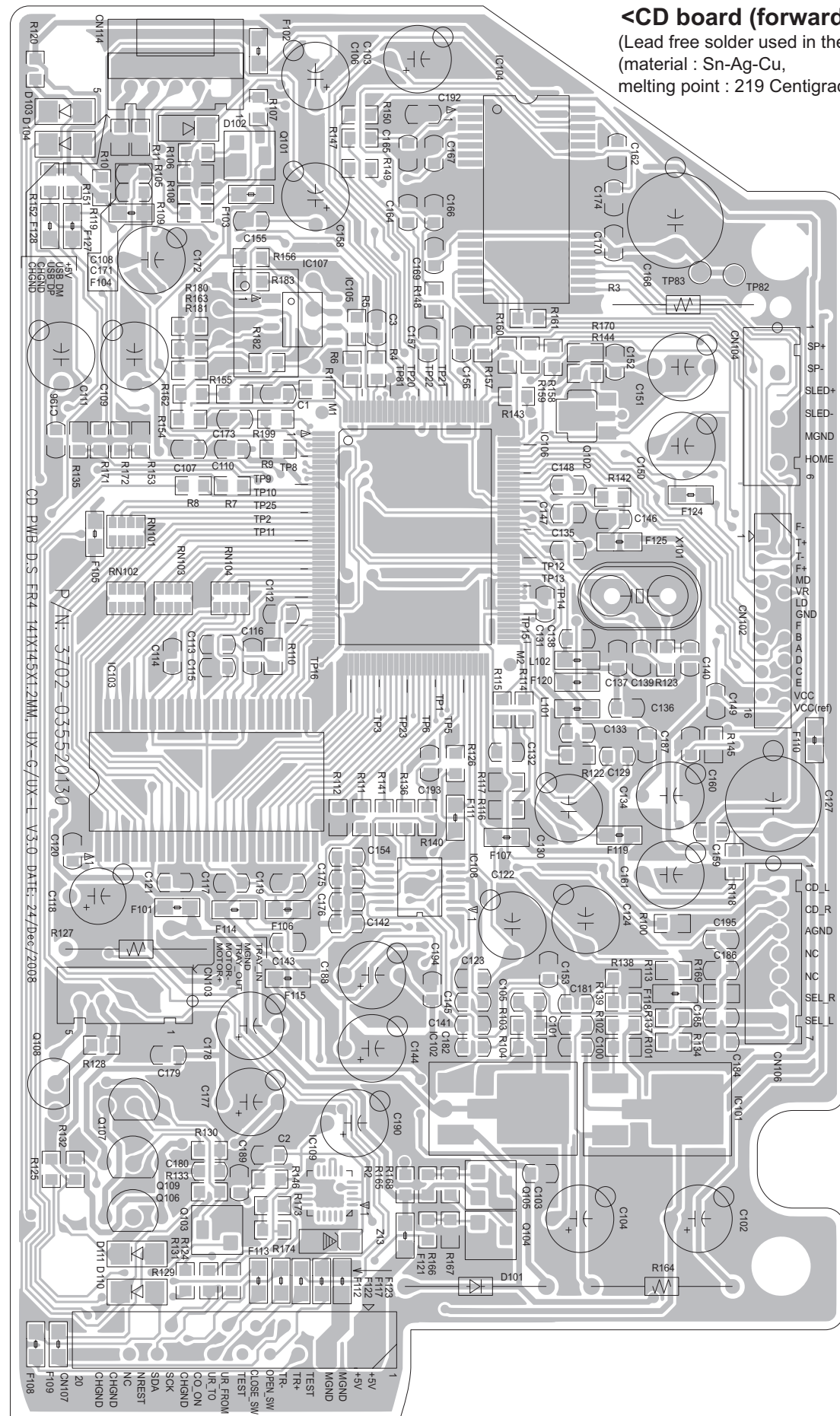


<Display/USB board (reverse side)>

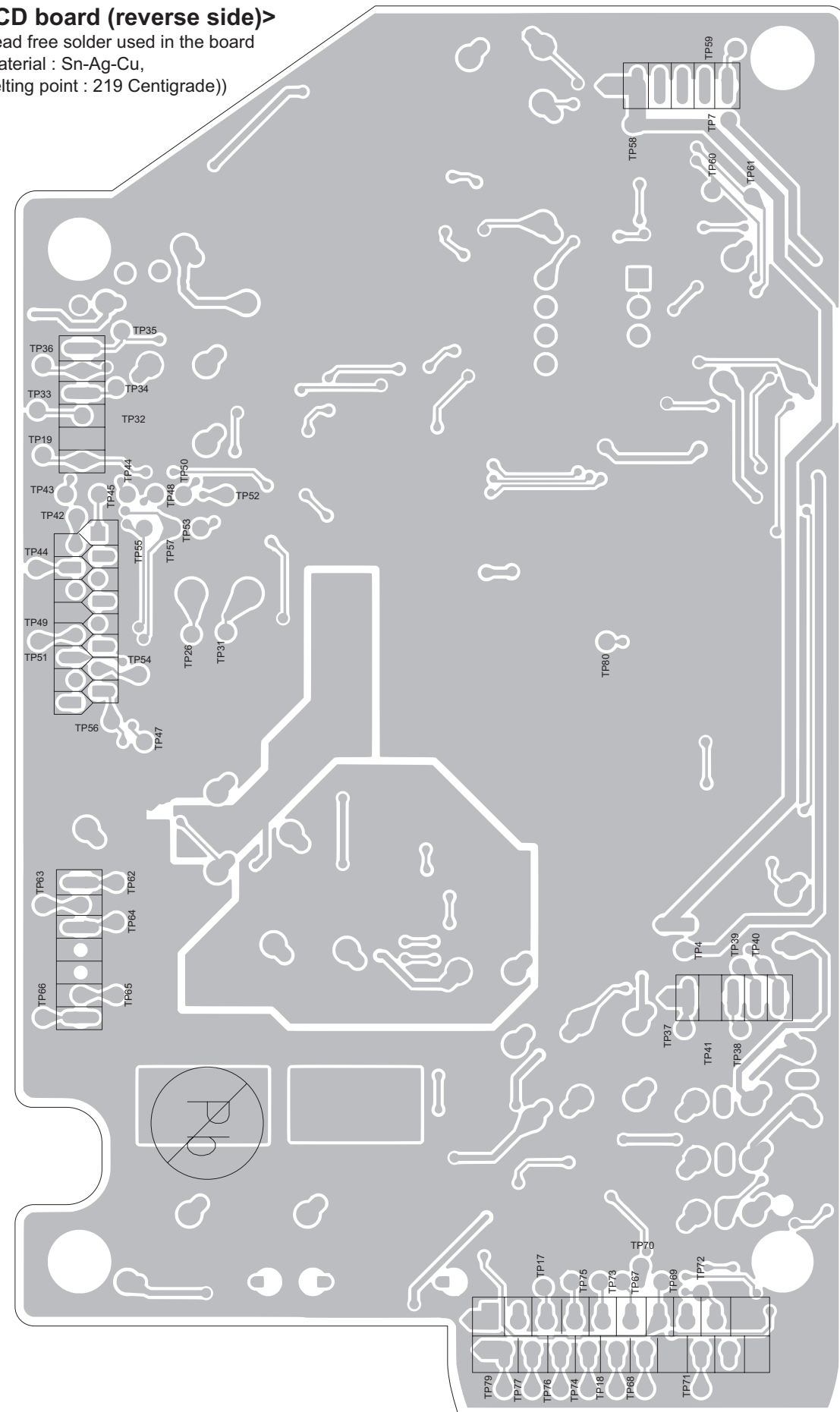
(Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade))



(Lead free solder used in the board
(material : Sn-Ag-Cu,
melting point : 219 Centigrade))



(Lead free solder used in the board
(material : Sn-Ag-Cu,
melting point : 219 Centigrade))



< MEMO >



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